0.40mm pitch, 0.80mm height, SlimStack B8 connectors with CleanPoint contact design have robust features that remove contaminants and prevent damage when subjected to harsh handling.

As future devices continue to increase in value and complexity, designers need to stabilize connections to avoid the need for costly rework and/or repair. Building reliability into connector designs for any devices is critical. In the production process of flex-to-board jumpers, flux or dust can sometimes settle on contacts and disrupt signal continuity. Molex’s B8 series includes a CleanPoint contact design with a beveled shape that can remove flux and other contaminants to provide a more stable electrical signal.

**Features and Advantages**

**Top Housing Wall**
Top housing wall (stopper) prevents the terminal from lifting up due to “zippering” or angled unmating.

**Angular Unmating (Zippering)**
Top housing wall

**Cover Nail**
Cover nail protects the housing from damage during blind mating or angled unmating (zippering). Mating tests on the outer wall of Molex’s B8 connectors demonstrate no damage to housing with up to 50N of force and 0.80mm displacement.

**Dual-Contact Design**
A dual-contact design on Molex’s SlimStack B8 series absorbs drop-shock discontinuity to help guarantee that a stable signal is maintained even when the device is subjected to rough handling.

**SlimStack B8 CleanPoint Contact**
Molex’s CleanPoint contact design provides superior electrical reliability and removes foreign materials such as flux.

**CleanPoint contact**

**Applications**

**Mobile Devices**
- Smartphones
- Tablet PCs
- Wearable Devices
- Portable Audio
- Portable Navigation Equipment

**Smartphone**

**Wearables**

**Portable Navigation**
SlimStack Board-to-Board Connectors, 0.40mm Pitch, B8 Series

Specifications

**REFERENCE INFORMATION**
Packaging: Embossed Tape and Reel
Designed In: Millimeters
RoHS: Yes
Halogen Free: Low-Halogen

**ELECTRICAL**
- Voltage (max.): 50V
- Current (max.): 0.3A per circuit
- Contact Resistance (max.): 80 milliohms
- Dielectric Withstanding Voltage: 250V AC
- Insulation Resistance (min.): 100 Megohms

**MECHANICAL**
- Durability (max.): 30 cycles

**PHYSICAL**
- Housing: LCP, UL 94V-0, Black
- Contact: Copper Alloy
- Plating:
  - Contact Area – Gold
  - Solder Tail Area – Gold
  - Underplating – Nickel
- Operating Temperature: -40 to +85°C

Dimensions

* Refer to drawing for detail dimension

**Receptacle**

0.40 x (N/2-1)+2.70mm
0.40mm (Pitch)
2.50mm

**Plug**

0.40 x (N/2-1)+1.87mm
0.40mm (Pitch)
2.10mm

Ordering Information

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<th>Order No.</th>
<th>Description</th>
<th>Mated Height (mm)</th>
<th>Mated Width (mm)</th>
<th>Circuits</th>
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<td>Connectors with nail edge inside housing edge</td>
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<td>2.50</td>
<td>10, 16, 20, 24, 30, 34, 40, 50</td>
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<tr>
<td>Plug</td>
<td></td>
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**: Circuit Size

**www.molex.com/link/slimstack.html**

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Order No. 987650-6531 Rev. 5
APN/0k/GF/2019.04
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